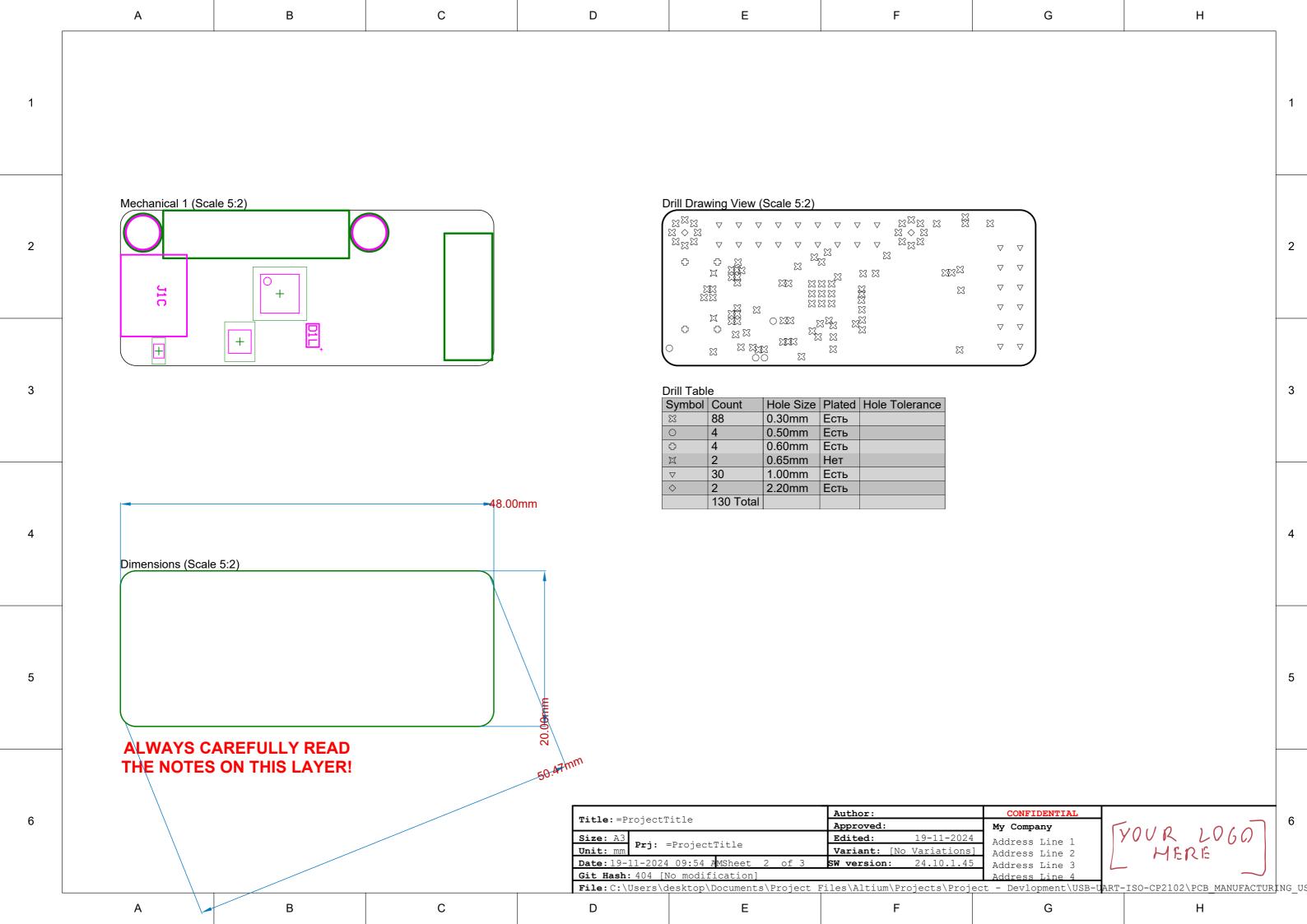
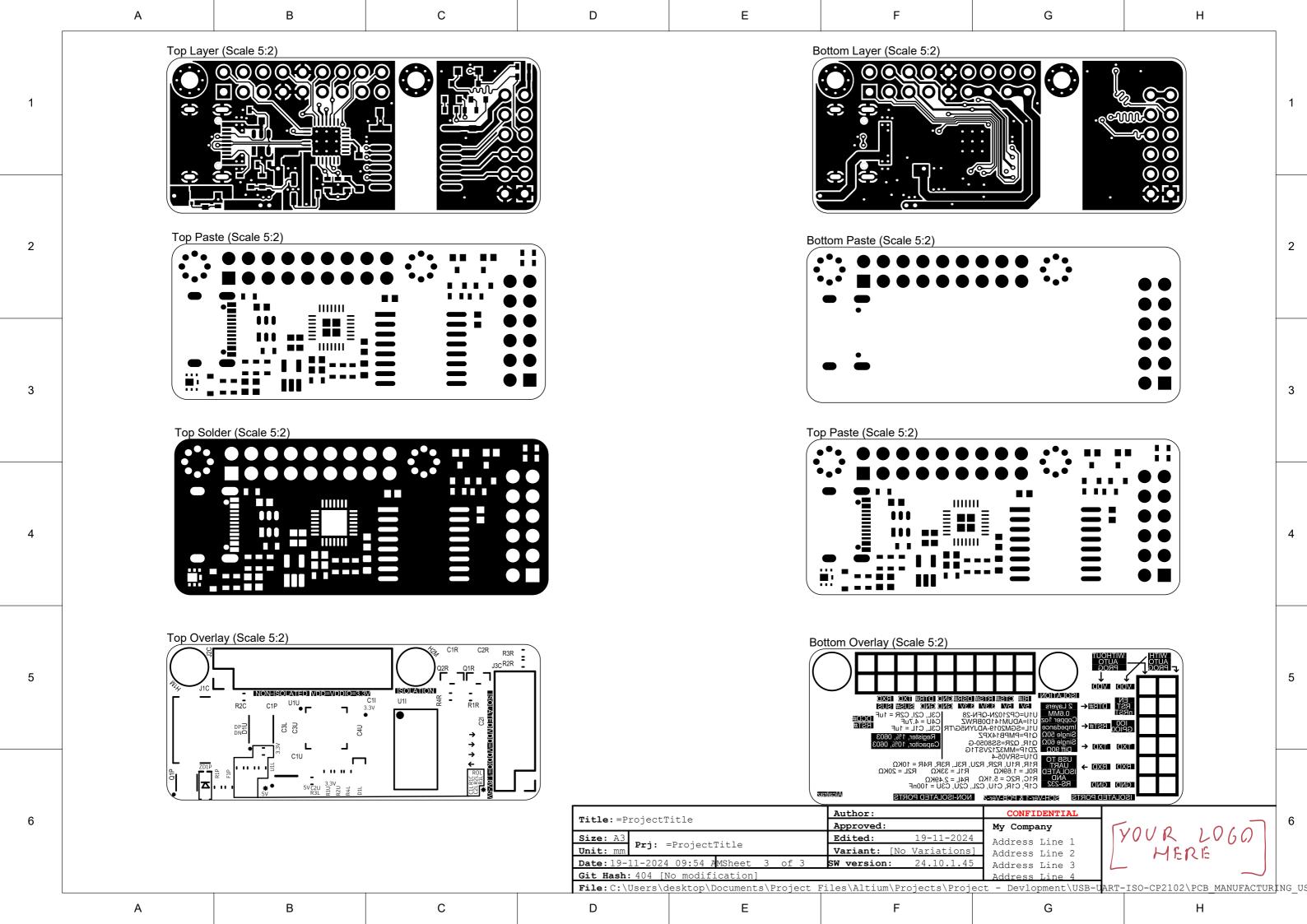
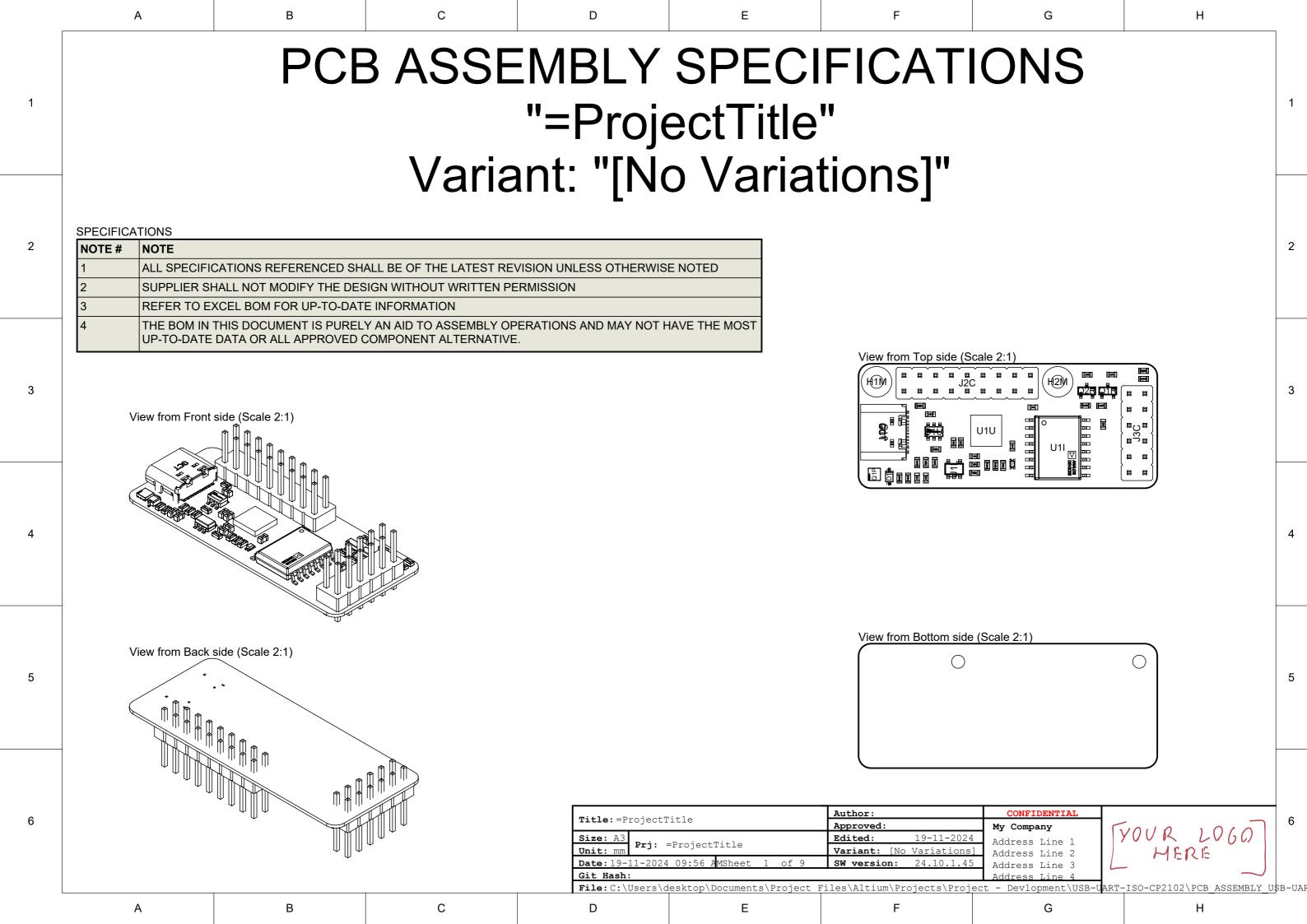
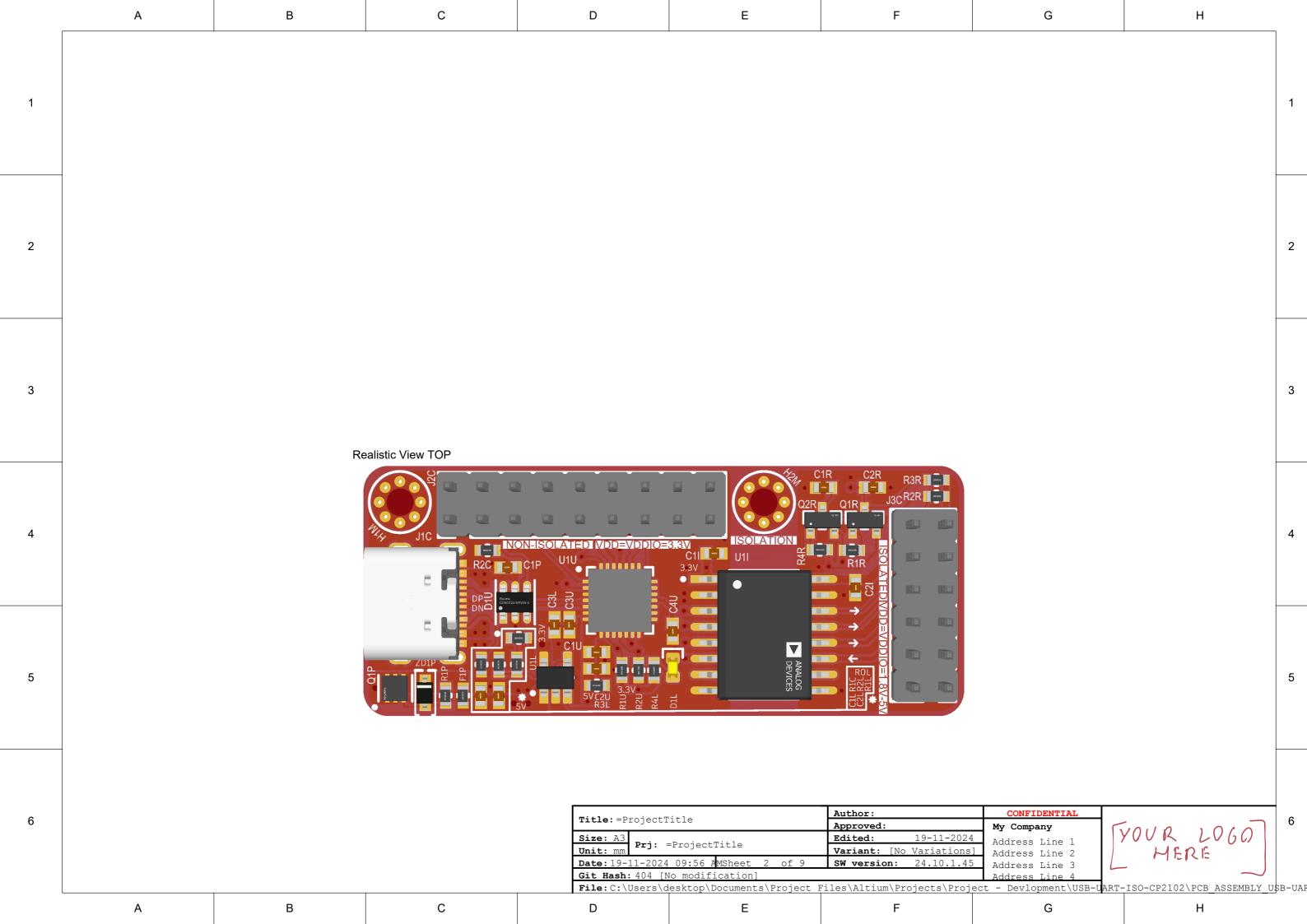


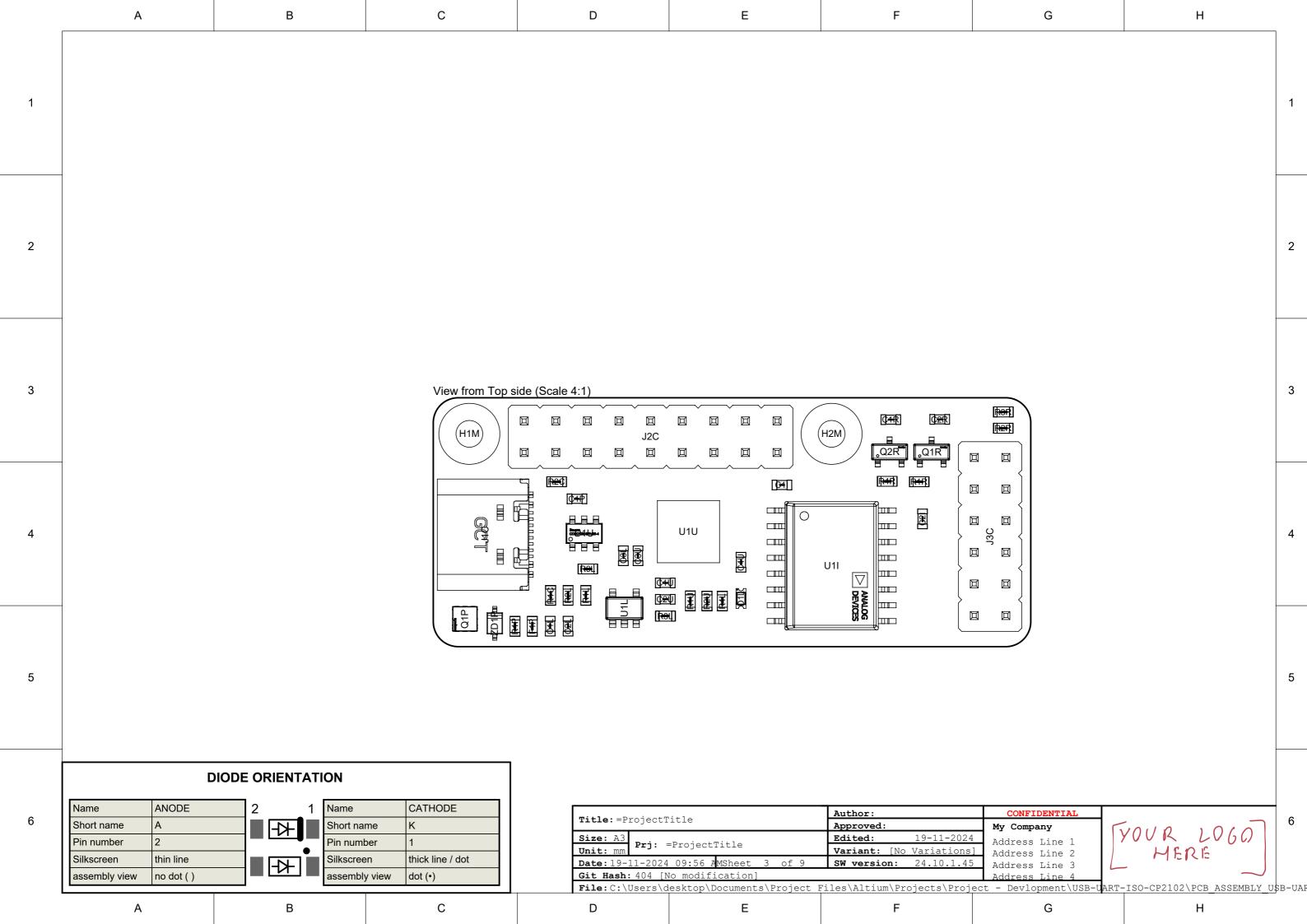
PCB MANUFACTURING SPECIFICATIONS "=ProjectTitle" **SPECIFICATIONS SPECIFICATIONS** NOTE# NOTE LENGHT 20.00mm **WIDTH** ALL SPECIFICATIONS REFERENCED ARE OF THE REVISION SPECIFIED IN THE TITLE BLOCK 48.00mm **LAYERS** SUPPLIER SHALL NOT MODIFY THE DESIGN OR APPROVED STACK-UP WITHOUT WRITTEN PERMISSION FR-4 **MATERIAL** ALL MATERIALS SHALL BE RoHS COMPLIANT AND FINAL PRODUCT SHALL BE ACCEPTABLE TO USE IN RoHS ASSEMBLY. RoHS LOGO SHALL BE MARKED IN SILKSCREEN INK BY THE SUPPLIER WHERE INDICATED BY **MATERIAL MIN TG** 130-140 THE TEXT "PLACE MARKINGS HERE" TRACK WIDTH/CLEARANCE 8 mils / 8 mils COPPER FOIL: REFER TO LAYER STACK LEGEND FOR Cu THICKNESS DETAILS. ALL Cu THICKNESSES ARE **THICKNESS** 1.6mm FINISHED AND INCLUDE BASE FOIL PLUS Cu PLATING ON PLATED LAYERS **COPPER THICKNESS** 35um (1oz) ELECTRICAL TEST: ALL PRINTED CIRCUITS SHALL BE 100% ELECTRICALLY TESTED FOR OPENS/SHORTS USING PROVIDED NETLIST. REJECTED PRINTED BOARDS MUST BE CLEARLY MARKED WITH NON-YES, TOP AND BOTTOM SOLDERMASK CONDUCTIVE. PERMANENT INK. **SOLDERMASK COLOR** MARKINGS: VENDOR MARKING AND DATE/LOT CODES SHALL BE LOCATED ON THE BOARD IN THE SILKSCREEN YES. TOP AND BOTTOM RESERVED AREA AS SPECIFIED IN THE GERBER LAYER "PCBM NOTES" BY THE TEXT "PLACE MARKINGS WHITE SILKSCREEN COLOR MARKINGS: THE SIDE ONTO WHICH PLACE THE MARKINGS IS AT THE SUPPLIER DISCRESSION UNLESS SURFACE FINISH **HASL LEAD FREE** OTHERWISE NOTED ONTO THE LAYER "PCBM NOTES" NO **GOLD FINGERS** SUPPLIER SHALL CHECK PCBM NOTES LAYER BEFORE ASKING FOR CLARIFICATIONS **CHAMFERING** NO MANUFACTURE TENTED/PLUGGED VIAS AS SPECIFIED IN THE GERBER FILES NO IMPEDANCE CONTROL NO HALF-CUT/CASTELLATED HOLES **BURIED/BLIND VIAS** NO NO VIAS FILLED WITH RESIN Layer Stack Legend Material Layer Thickness Dielectric Material Type Gerber NO **CARBON MASK** Top Overlay GTO COUNTERSINKS/COUNTERBORES NO Surface Material Top Solder Solder Mask GTS NO **Z-AXIS MILLING** Copper Top Layer Signal GTL PEELABLE SOLDERMASK NO Core 0.50mm FR-4 Dielectric **GBL** 0.04mm Signal Solder Mask GBS Surface Material Bottom Solder 0.02mm Solder Resist GBO **Bottom Overlay** Legend Total thickness: 0.60mm NON-COPPER LAYER THICKNESS FOR REFERENCE ONLY LAYERS OF TYPE "INTERNAL PLANE" ARE NEGATIVE Author: Title: =ProjectTitle Approved: My Company Prj: =ProjectTitle Address Line 1 Variant: Address Line 2 Date: 19-11 SW version: Address Line 3 С G В

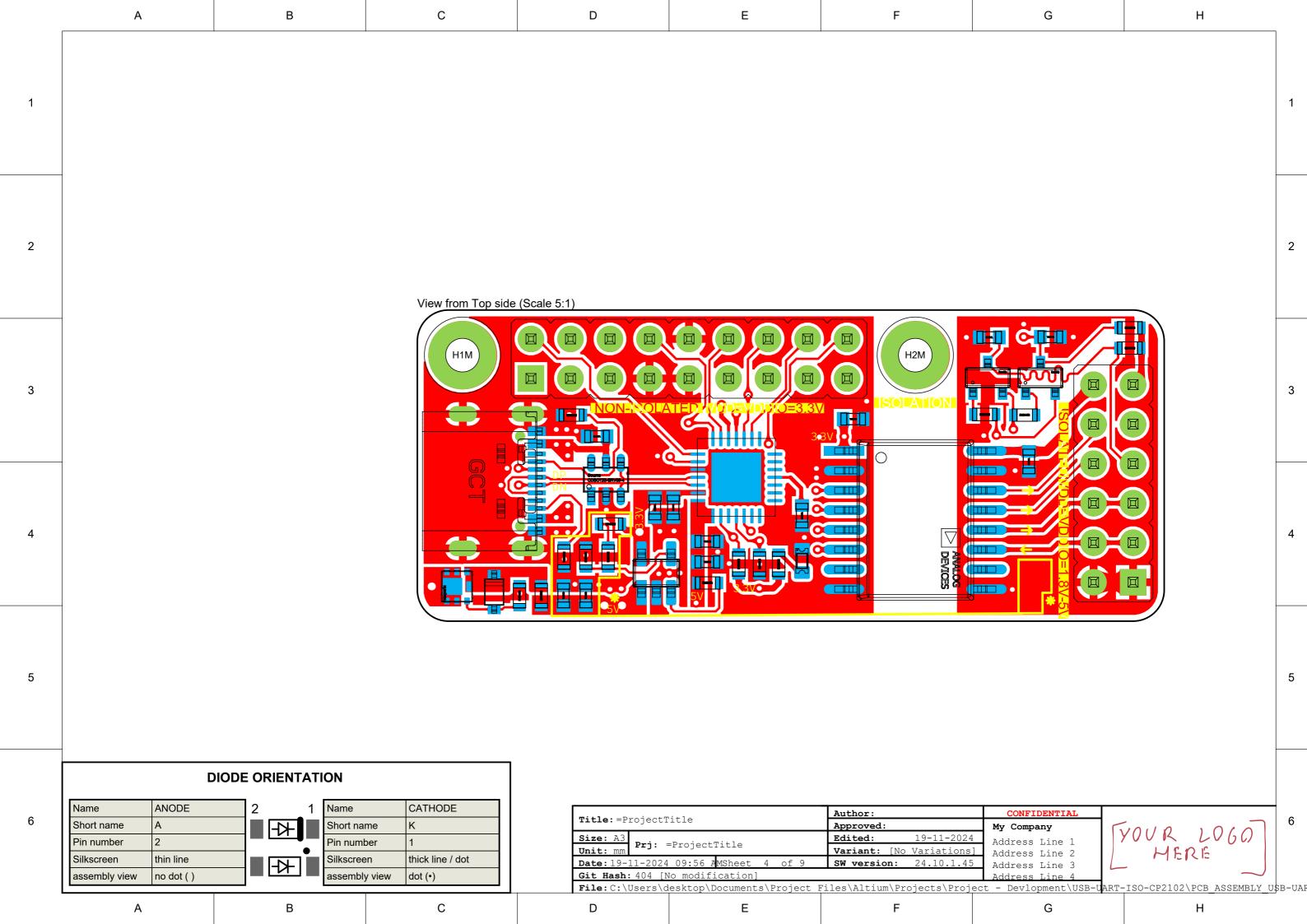


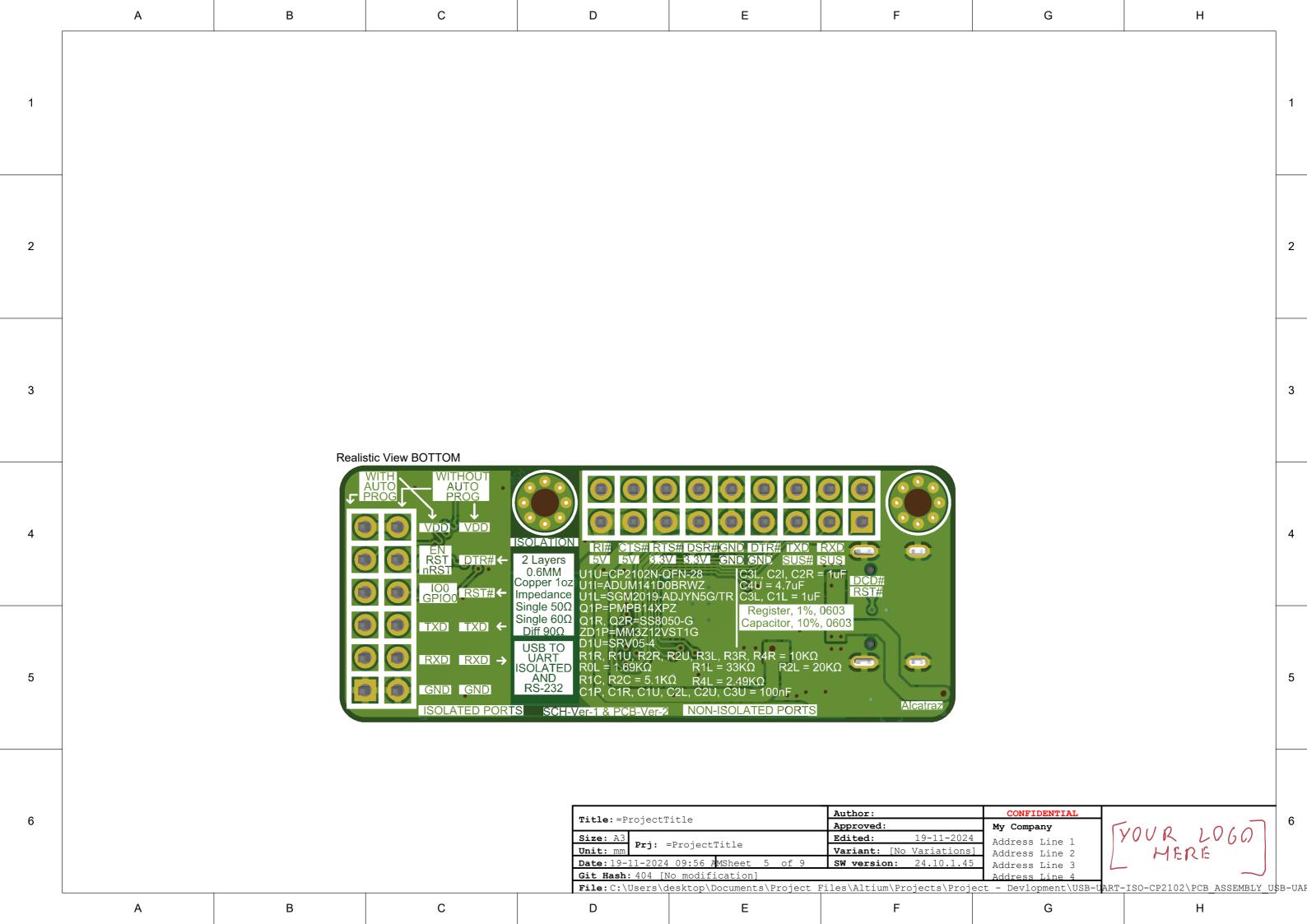


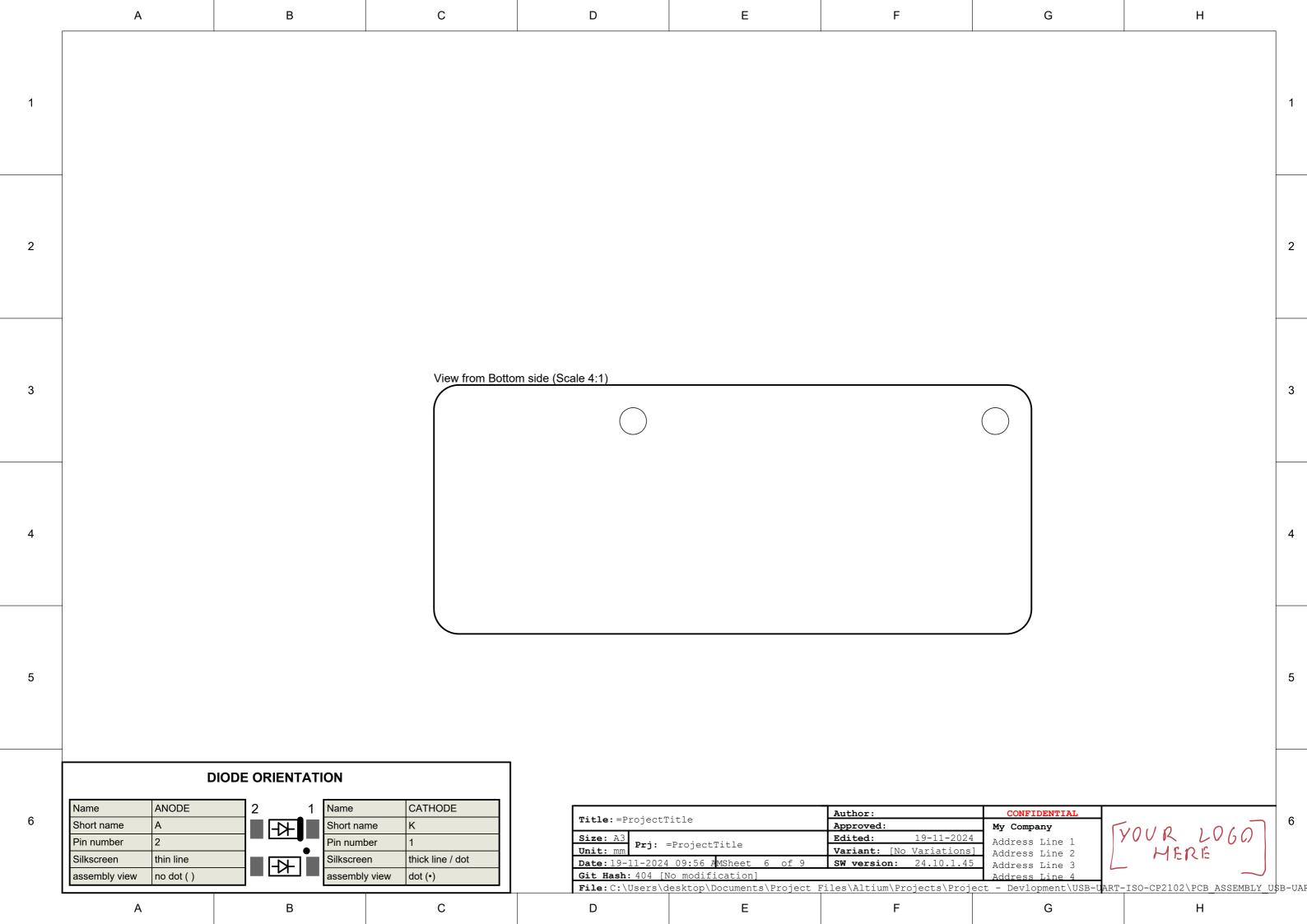


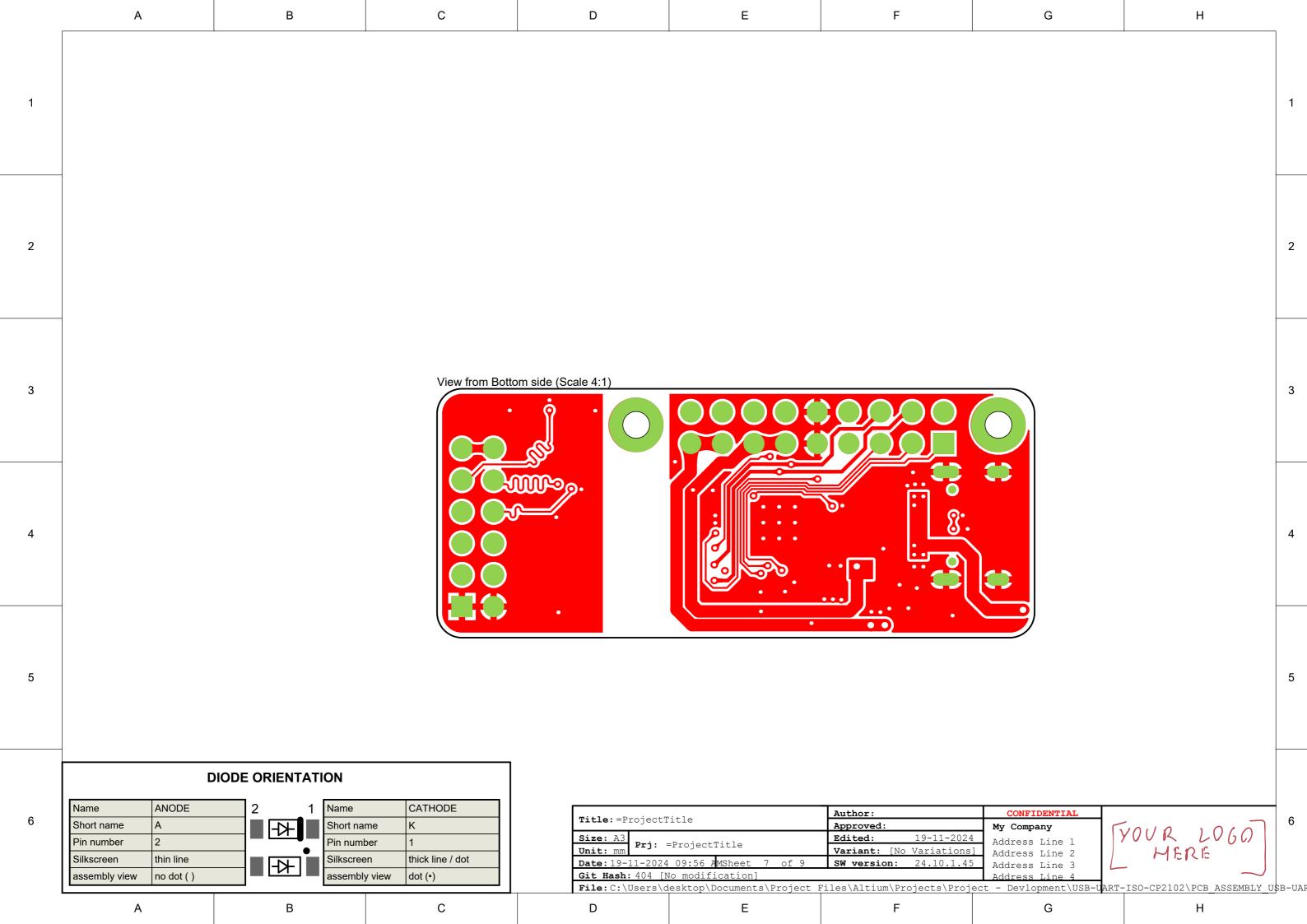


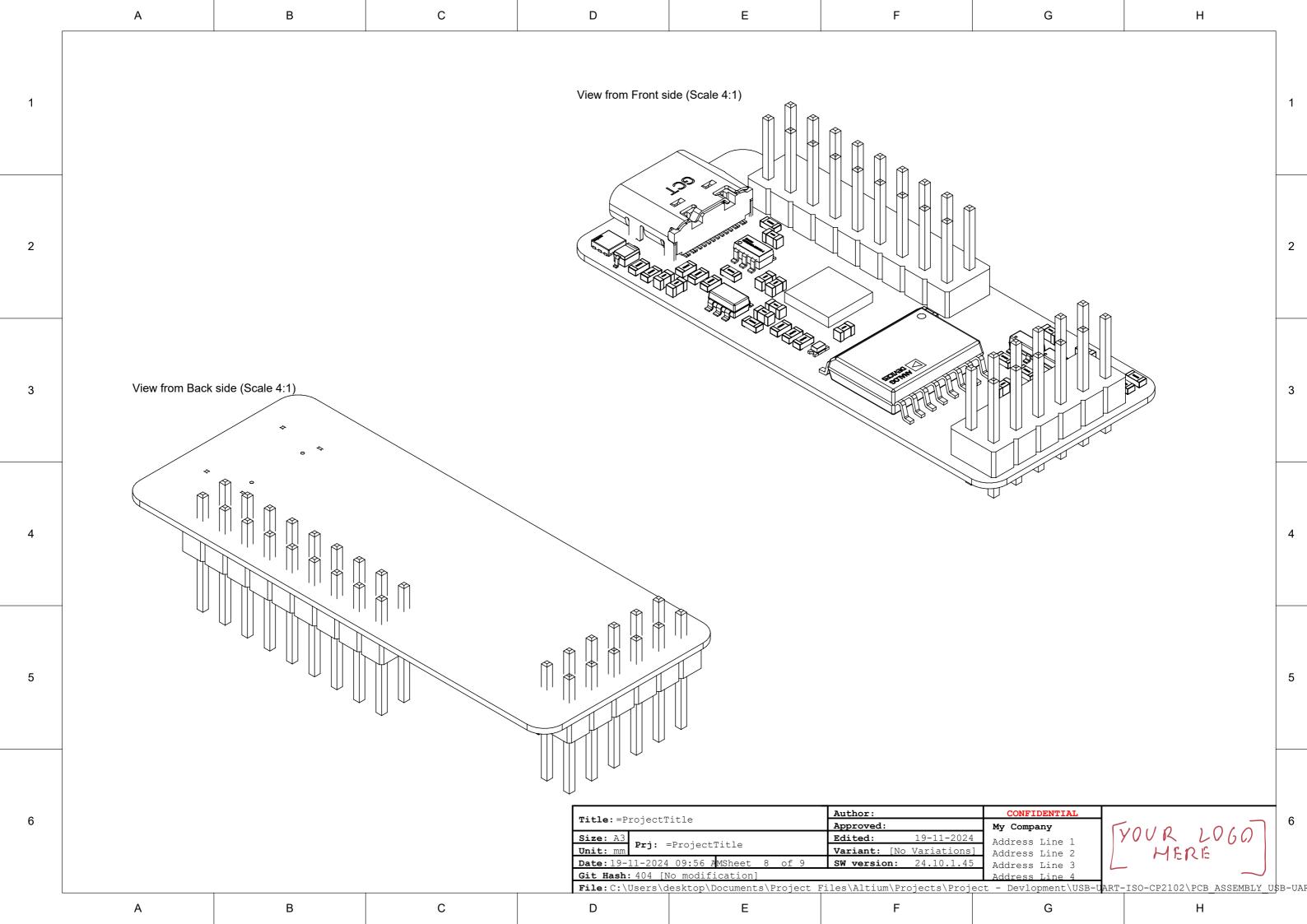












	А	В	С	D	E	F	G	Н		
1									1	
	Bill Of Materials									
2	Line # Description		Designator	Quantity	Manufacturer Part Number 1	Part Number	Layer			
	Ceramic Capac	citor, Multilayer, Ceramic, 6.3V, 109 1uF, Surface Mount, 0		C1I	1	C0603C105K9PACTU			2	
	Multilayer Ceramic Capacitor, 10 uF, 10 V, ± 10%, X5R, 0603 [1608 Metric] Multilayer Ceramic Capacitor, 0.1 uF, 10 V, ± 10%, X7R, 0603 [1608 Metric]			C1L	1					
			0%, X7R, 0603 [1608 Metric]	C1P, C1U, C2L,	C2U 4	C0603C104K8RAC786				
		Cap Cer 0.1UF 6.3V X7R 0603		C1R, C3U	2	KGM15AR70J104KM				
3		Ceramic Capacitor, Multilayer, Ceramic, 10V, 10% +Tol, 10% -Tol, X5R, 15% TC, 1uF, 0603 Multilayer Ceramic Capacitor, 10 uF, 6.3 V, ± 10%, X5R, 0603 [1608 Metric] Multilayer Ceramic Capacitor, 4.7 uF, 10 V, ± 10%, X5R, 0603 [1608 Metric]		C2I, C2R	2					
				C3L C4U	1	CL10A106KQ8NNNC CL10A475KP8NNNC				
	iviuitilayer C	LED 0603 YELLOW S		D1L	1	CL TUA47 SKPOININIC				
		TVS DIODE 5V 15V SOT23-6 Fuse PPTC SMD 0603 USB Connector Type C SMT 16 Pin (Power pins joints = 12 pins)		D1U F1P	1				3	
				J1C	1					
				J2C	1					
				J3C	1					
	PMPB14XPZ Trans Gp Bjt NPN 25V 1.5A 300MW 3-PIN SOT-23 T/r		Q1P Q1R, Q2R	1	PMPB14XPZ SS8050-G					
4		Surface Mount Thick Film Chip Resistor 0603 Case 1.69K Ohms 1% Tolerance 100 PPM SMD Chip Resistor, 5.1 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose Res Thick Film 0603 33K Ohm 1% 0.1W(1/10W) ±100ppm/C Pad SMD Automotive T/R SMD Chip Resistor, 100 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose SMD Chip Resistor, 10 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose SMD Chip Resistor, 20 kOhm, ± 1%, 100 mW, 0603 [1608 Metric], Thick Film, General Purpose		R0L	1	MCR03EZPFX1691				
	SMD Chip Re			R1C, R2C	2	CRCW06035K10FKEA			4	
	Res Thick Film			R1L	1	ERJ-3EKF3302V				
	SMD Chip Re			R1P	1	AC0603FR-07100KL				
	SMD Chip Re			R1R, R1U, R2R, R2U, R3	8L, R3R, R4R 7	RC0603FR-0710KL				
				R2L	1	CR0603-FX-2002ELF				
5	Res Thick Film	Res Thick Film 0603 2.49K Ohm 1% 1/10W ±100ppm/°C Molded SMD SMD Paper T/R		R4L	1					
		DGTL ISO 3750VRMS 4CH (U1I	1					
	Single-Chin II	LDO U-Reg Adj 0, 3A SO ISB to UART Bridge, 1024 Bytes EE		U1L	1					
		QFN, Tube		U1U	1				5	
	MM3Z12V8	ST1G Zener Diode, 12V 2% 200 m ¹ Semiconductor MM3Z12		ZD1P	1					
6	Please consider LCSC (立创商城) as our first supplier BOM FOR REFERENCE ONLY ALWAYS REFER TO THE LATEST EXCEL BOM PROVIDED									
						Author:	CONFIDENTIAL			
				Title: =ProjectTitle Size: A3 Unit: mm Prj: =ProjectTitle Date: 19-11-2024 09:56 AMSheet 9 of 9 Git Hash: 404 [No modification] File: C:\Users\desktop\Documents\Project F		Approved:	My Company	50000 100	01/0 10(0) 6	
						Edited: 19-1 Variant: [No Variate of Variate	1-2024 Address Line 1	YOUR LOG HERE	W	
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